Hex inverter with open-drain outputs | 74LVC06A

FEATURES

- 5 V tolerant inputs and outputs (open drain) for interfacing with 5 V logic
- Wide supply voltage range from 1.65 to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Complies with JEDEC standard no. 8-1A.

DESCRIPTION

The 74LVC06A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 to 5 V environment.

The 74LVC06A provides six inverting buffers.

The outputs of the 74LVC06A devices are open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	CONDITIONS	TYP.	UNIT
t_{PLZ}/t_{PZL}	propagation delay nA to nY	C_L = 50 pF; V_{CC} = 3.3 V	2.3	ns
C_I	input capacitance		5.0	pF
C_{PD}	power dissipation capacitance per gate	V_I = GND to V_{CC}; note 1	8.0	pF

Note

1. C_{PD} is used to determine the dynamic power dissipation (P_D in µW).

   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

   f_i = input frequency in MHz;

   f_o = output frequency in MHz;

   C_L = output load capacitance in pF;

   V_{CC} = supply voltage in Volts;

   $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	nY
L	Z
H	L

Note

1. H = HIGH voltage level;

   L = LOW voltage level;

   Z = high impedance OFF-state.

Hex inverter with open-drain outputs 74LVC06A

ORDERING INFORMATION

TYPE NUMBER	PACKAGES				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC06AD	−40 to +85 °C	14	SO	plastic	SOT108-1
74LVC06APW		14	TSSOP	plastic	SOT402-1

PINNING

PIN	SYMBOL	DESCRIPTION
1, 3, 5, 9, 11 and 13	1A to 6A	data inputs
2, 4, 6, 8, 10 and 12	1Y to 6Y	data outputs
7	GND	ground (0 V)
14	V_{CC}	DC supply voltage

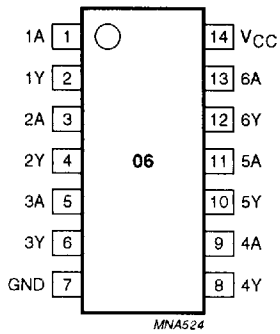


Fig.1 Pin configuration.

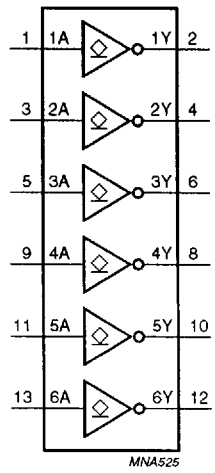


Fig.2 Logic symbol.

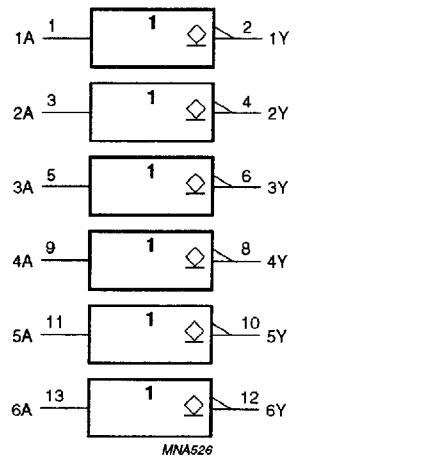


Fig.3 IEC logic symbol.

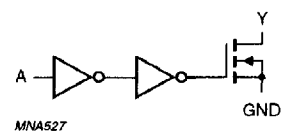


Fig.4 Logic diagram (one gate).

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN.	MAX.	
V_{CC}	DC supply voltage		1.65	5.5	V
V_I	DC input voltage		0	5.5	V
V_O	DC output voltage	active mode	0	V_{CC}	V
		high-impedance mode	0	5.5	V
T_{amb}	operating ambient temperature		−40	+85	°C
t_r, t_f	input rise and fall ratios	V_{CC} = 1.65 to 2.7 V	0	20	ns/V
		V_{CC} = 2.7 to 5.5 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	DC supply voltage		−0.5	+6.5	V
I_{IK}	DC input diode current	$V_I < 0$	–	−50	mA
V_I	DC input voltage	note 1	−0.5	+6.5	V
I_{OK}	DC output clamping diode current	$V_O < 0$	–	−50	mA
V_O	DC output voltage	active mode; note 1	−0.5	V_{CC} + 0.5	V
		high-impedance mode; note 1	−0.5	+6.5	V
I_O	DC output sink current	V_O = 0 to V_{CC}	–	50	mA
I_{CC}, I_{GND}	DC V_{CC} or GND current		–	±100	mA
T_{stg}	storage temperature		−65	+150	°C
P_{tot}	power dissipation per package				
	SO package	above 70 °C derate linearly with 8 mW/K	–	500	mW
	TSSOP package	above 60 °C derate linearly with 5.5 mW/K	–	500	mW

Note

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC CHARACTERISTICS

Over recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		T_{amb} (°C)			UNIT
		OTHER	V_{CC} (V)	−40 to +85			
				MIN.	TYP.(1)	MAX.	
V_{IH}	HIGH-level input voltage		1.65 to 1.95	V_{CC}	–	–	V
			2.3 to 2.7	1.7	–	–	V
			2.7 to 3.6	2.0	–	–	V
			4.5 to 5.5	$0.7 \times V_{CC}$	–	–	V
V_{IL}	LOW-level input voltage		1.65 to 1.95	–	–	GND	V
			2.3 to 2.7	–	–	0.7	V
			2.7 to 3.6	–	–	0.8	V
			4.5 to 5.5	–	–	$0.30 \times V_{CC}$	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		I_O = 100 µA	1.65 to 5.5	–	–	0.20	V
		I_O = 4 mA	1.65	–	–	0.45	V
		I_O = 8 mA	2.3	–	–	0.3	V
		I_O = 12 mA	2.7	–	–	0.4	V
		I_O = 24 mA	3.0	–	–	0.55	V
		I_O = 32 mA	4.5	–	–	0.55	V
I_I	input leakage current	V_I = 5.5 V or GND	3.6	–	±0.1	±5	µA
I_{OZ}	3-state output OFF-state current	$V_I = V_{IH}$ or V_{IL}; V_O = 5.5 V or GND	3.6	–	0.1	±10	µA
I_{off}	power-off leakage current	V_I or V_O = 6.5 V	0.0	–	±0.1	±10	µA
I_{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; I_O = 0	5.5	–	0.1	10	µA
ΔI_{CC}	additional quiescent supply current per input pin	$V_I = V_{CC}$ − 0.6 V; I_O = 0	2.3 to 5.5	–	5	500	µA

Note

1. All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C.

AC CHARACTERISTICS

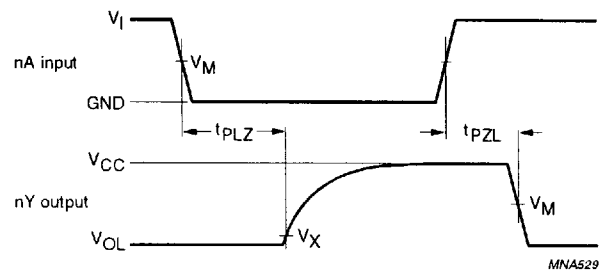
GND = 0 V; $V_{CC} \leq 2.7$ V and $t_r = t_f \leq 2$ ns; $V_{CC} \geq 2.7$ V and $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	TEST CONDITIONS		T_{amb} (°C)			UNIT
		WAVEFORMS	V_{CC} (V)	−40 to +85			
				MIN.	TYP.(1)	MAX.	
t_{PLZ}/t_{PZL}	propagation delay nA to nY	see Figs 5 and 6	1.65 to 1.95	–	2.9	–	ns
			2.3 to 2.7	0.5	1.8	3.1	ns
			2.7	0.5	2.5	3.9	ns
			3.0 to 3.6	0.5	2.3	3.7	ns
			4.5 to 5.5	0.5	1.7	3.4	ns

Note

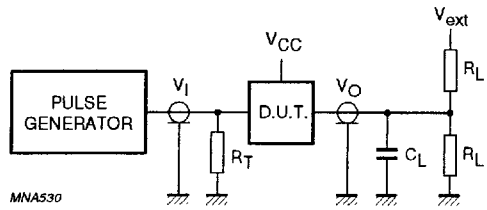
1. All typical values are measured at T_{amb} = 25 °C and at V_{CC} respectively 1.8, 2.5, 2.7, 3.3 and 5.0 V.

AC WAVEFORMS



V_{CC}	V_M	V_X
<2.7 V	0.5 × V_{CC}	V_{OL} + 0.15 V
≥2.7 to 3.6 V	1.5 V	V_{OL} + 0.3 V
≥4.5 to 5.5 V	0.5 × V_{CC}	V_{OL} + 0.3 V

Fig.5 The input nA to output nY propagation delays.

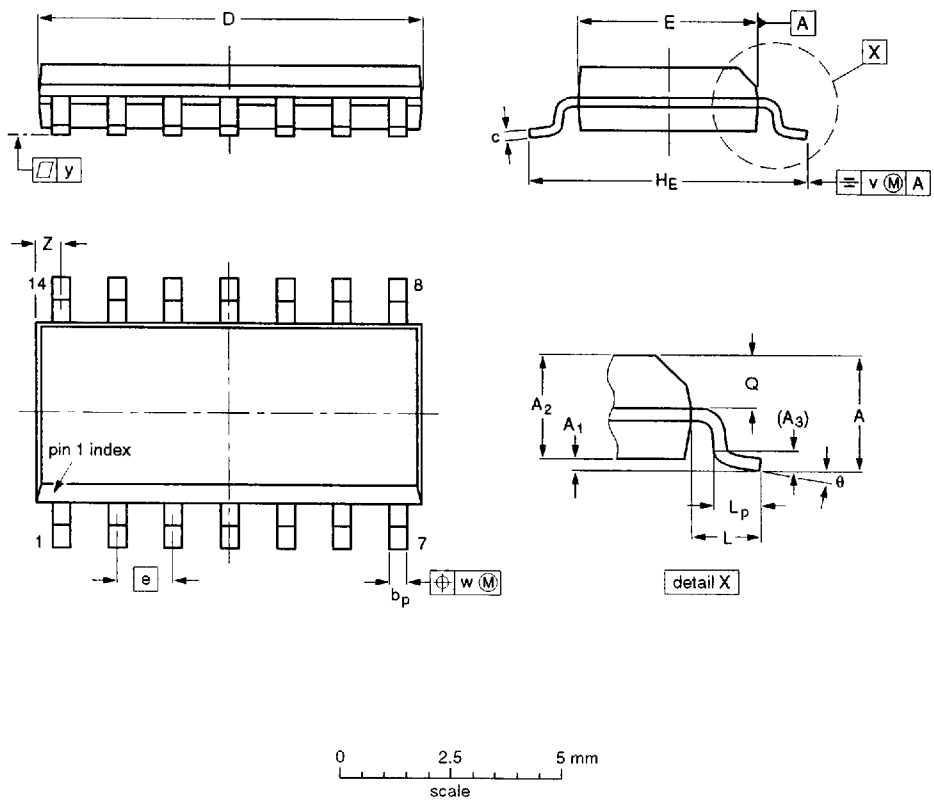


V_{CC}	V_{ext}	V_I	C_L	R_L
1.65 to 1.95 V	$2 \times V_{CC}$	V_{CC}	30 pF	1 kΩ
2.3 to 2.7 V	$2 \times V_{CC}$	V_{CC}	30 pF	500 Ω
2.7 V	6 V	2.7 V	50 pF	500 Ω
3.3 to 3.6 V	6 V	2.7 V	50 pF	500 Ω
4.5 to 5.5 V	$2 \times V_{CC}$	V_{CC}	50 pF	500 Ω

Fig.6 Load circuitry for switching times.

PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

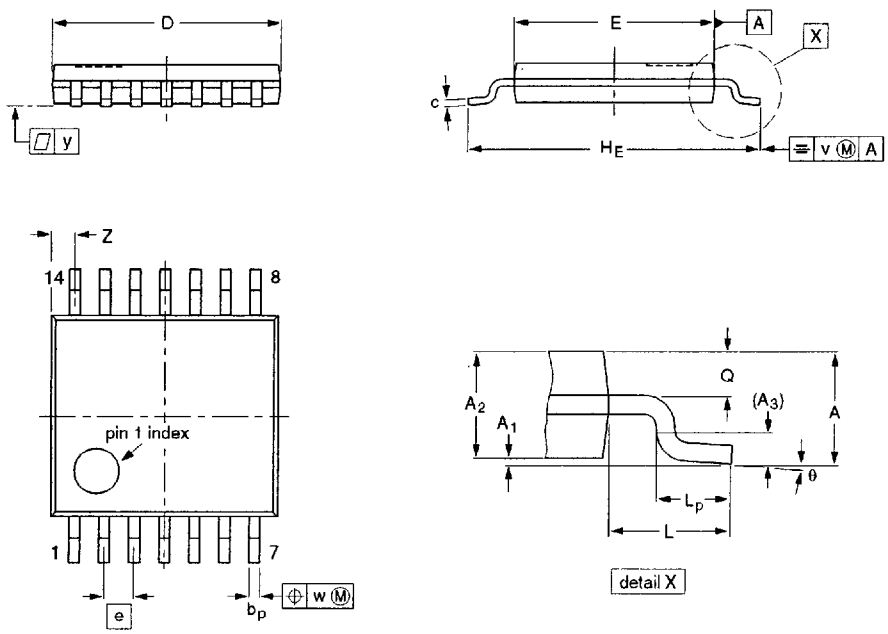
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

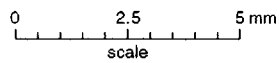
Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06	MS-012				~~97-05-22~~ 99-12-27

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT402-1		MO-153				~~95-04-04~~ 99-12-27

SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 230 °C.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

  The footprint must incorporate solder thieves at the downstream end.
- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.
A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW(1)
BGA, LFBGA, SQFP, TFBGA	not suitable	suitable
HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable(2)	suitable
PLCC(3), SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended(3)(4)	suitable
SSOP, TSSOP, VSO	not recommended(5)	suitable

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.